

Diode

Silicon Carbide Schottky Diode

IDM02G120C5

5th Generation thinQ!™ 1200 V SiC Schottky Diode

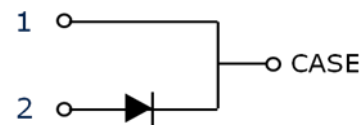
Final Data Sheet

Rev. 2.0, 2015-06-22

SiC Schottky Diode

Features:

- Revolutionary semiconductor material - Silicon Carbide
- No reverse recovery current / No forward recovery
- Temperature independent switching behavior
- Low forward voltage even at high operating temperature
- Tight forward voltage distribution
- Excellent thermal performance
- Extended surge current capability
- Specified dv/dt ruggedness
- Qualified according to JEDEC¹⁾ for target applications
- Pb-free lead plating; RoHS compliant



Benefits

- System efficiency improvement over Si diodes
- Enabling higher frequency / increased power density solutions
- System size/cost savings due to reduced heatsink requirements and smaller magnetics
- Reduced EMI
- Highest efficiency across the entire load range
- Robust diode operation during surge events
- High reliability
- RelatedLinks: www.infineon.com/sic



Applications

- Solar inverters
- Uninterruptable power supplies
- Motor drives
- Power Factor Correction



Package pin definitions

- Pin 1 and backside – cathode
- Pin 2 – anode

Key Performance and Package Parameters

Type	V _{DC}	I _F	Q _C	T _{j,max}	Marking	Package
IDM02G120C5	1200V	2A	14nC	175°C	D0212C5	PG-TO252-2

1) J-STD20 and JESD22

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Maximum ratings

Parameter	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	1200	V
Continuous forward current for $R_{th(j-c,max)}$ $T_C = 170^{\circ}C$, D=1 $T_C = 135^{\circ}C$, D=1 $T_C = 25^{\circ}C$, D=1	I_F	2 7 14	A
Surge non-repetitive forward current, sine halfwave $T_C=25^{\circ}C$, $t_p=10ms$ $T_C=150^{\circ}C$, $t_p=10ms$	$I_{F,SM}$	37 31	
Non-repetitive peak forward current $T_C = 25^{\circ}C$, $t_p=10 \mu s$	$I_{F,max}$	344	
i^2t value $T_C = 25^{\circ}C$, $t_p=10 ms$ $T_C = 150^{\circ}C$, $t_p=10 ms$	$\int i^2 dt$	7.0 4.9	A ² s
Diode dv/dt ruggedness $V_R=0...960 V$	dv/dt	80	V/ns
Power dissipation $T_C = 25^{\circ}C$	P_{tot}	98	W
Operating and storage temperature	$T_J; T_{stg}$	-55...175	$^{\circ}C$
Soldering temperature, Wave- and reflowsoldering allowed (reflow MSL1)	T_{sold}	260	

Thermal Resistances

Thermal Resistance						
Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Characteristic						
Diode thermal resistance, junction – case	$R_{th(j-c)}$		-	1.2	1.5	K/W
Thermal resistance, junction – ambient	$R_{th(j-a)}$	SMD version, device on PCB, minimal footprint	-	-	62	
		SMD version, device on PCB, 6 cm ² cooling area ²⁾		35		

²⁾ Device on 40 mm*40mm*1.5 epoxy PCB FR4 with 6cm² (one layer, 70μm thick) copper for cathode connection. PCB is vertical without air stream cooling.

Electrical Characteristics, at T_j=25°C, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Static Characteristic						
DC blocking voltage	V_{DC}	$T_j = 25^{\circ}C$	1200	-	-	V
Diode forward voltage	V_F	$I_F = 2\text{ A}, T_j = 25^{\circ}C$	-	1.4	1.65	V
		$I_F = 2\text{ A}, T_j = 150^{\circ}C$	-	1.7	2.30	
Reverse current	I_R	$V_R = 1200\text{ V}, T_j = 25^{\circ}C$		1.2	18	μA
		$V_R = 1200\text{ V}, T_j = 150^{\circ}C$		6	90	

AC Characteristics, at T_j=25°C, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Dynamic Characteristics						
Total capacitive charge	Q _C	V _R = 800 V, T _j =150°C $Q_C = \int_0^{V_R} C(V)dV$	-	14	-	nC
Total Capacitance	C	V _R =1 V, f=1 MHz	-	182	-	pF
		V _R =400 V, f=1 MHz	-	13	-	
		V _R =800 V, f=1 MHz	-	10	-	

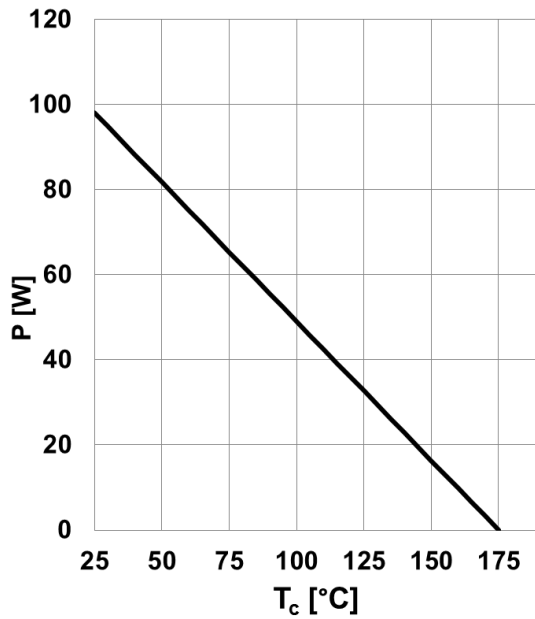


Figure 1. **Power dissipation as a function of case temperature, $P_{tot}=f(T_c)$, $R_{th(j-c),max}$**

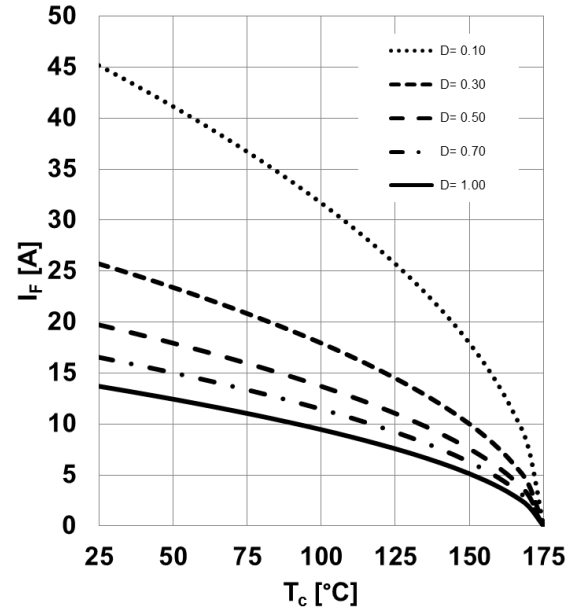


Figure 2. **Diode forward current as function of temperature, $T_j \leq 175^\circ\text{C}$, $R_{th(j-c),max}$, parameter D =duty cycle, V_{th} , R_{diff} @ $T_j=175^\circ\text{C}$**

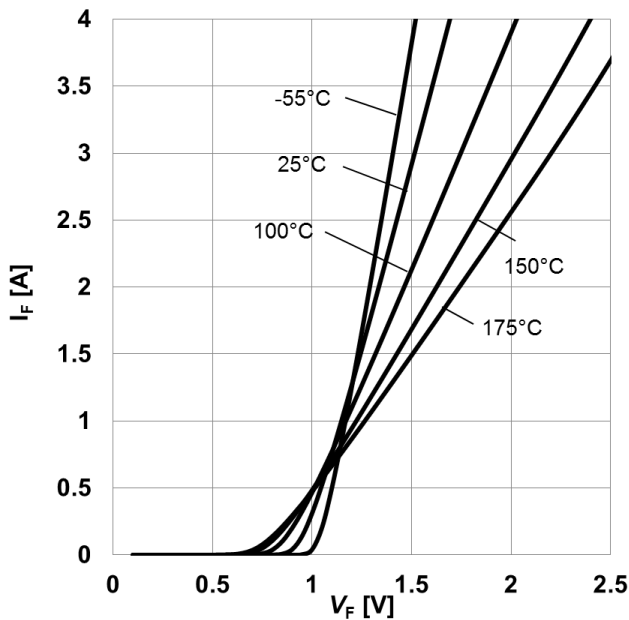


Figure 3. **Typical forward characteristics, $I_F=f(V_F)$, $t_p=10\text{ }\mu\text{s}$, parameter: T_j**

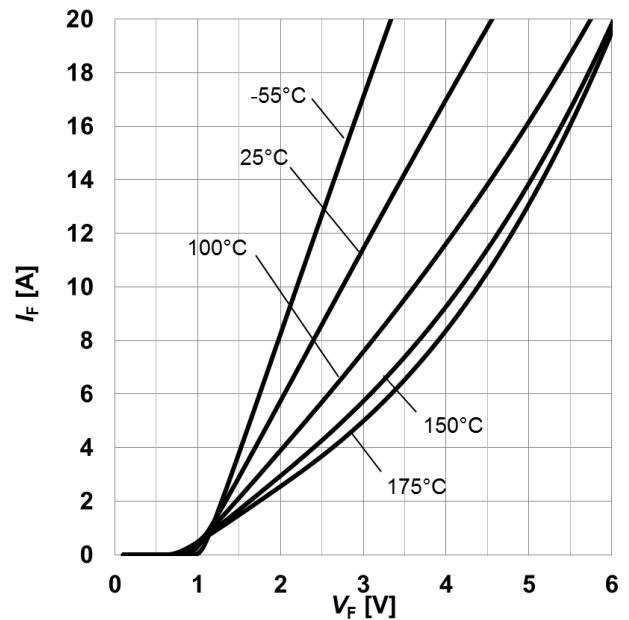


Figure 4. **Typical forward characteristics in surge current, $I_F=f(V_F)$, $t_p=10\text{ }\mu\text{s}$, parameter: T_j**

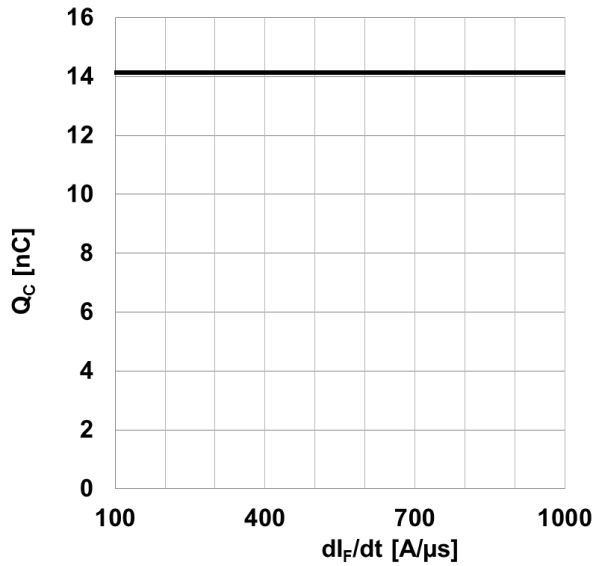


Figure 5. **Typical capacitance charge as function of current slope**¹, $Q_C=f(dI_F/dt)$, $T_J=150^{\circ}\text{C}$

1) Only capacitive charge, guaranteed by design.

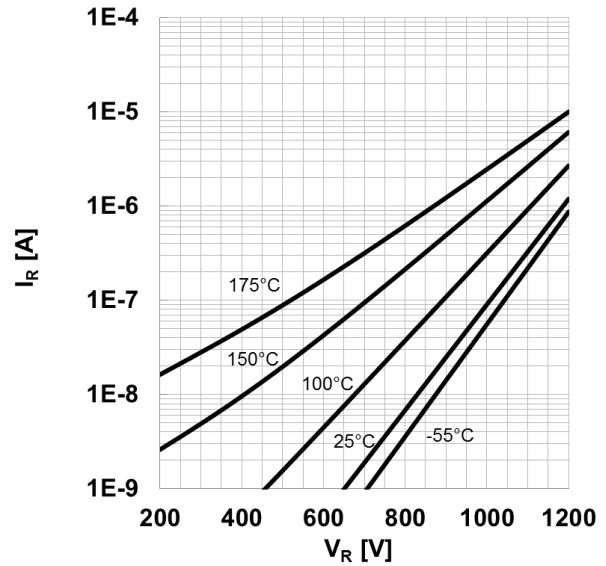


Figure 6. **Typical reverse current as function of reverse voltage**, $I_R=f(V_R)$, parameter: T_J

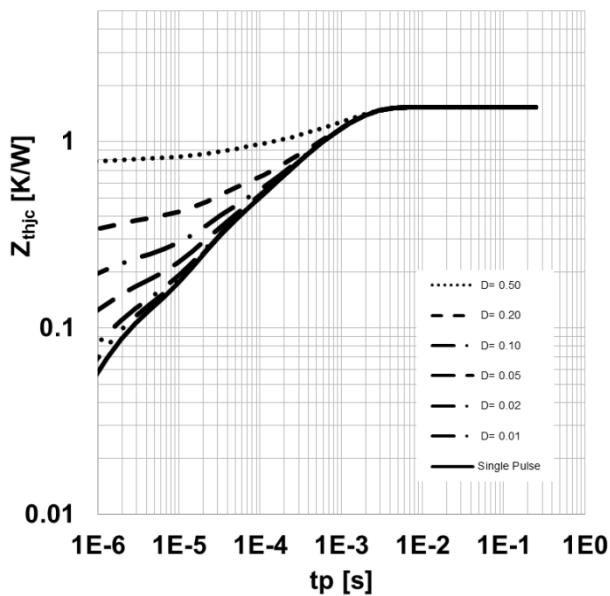


Figure 7. **Max. transient thermal impedance**, $Z_{th,jc}=f(t_p)$, parameter: $D=t_p/T$

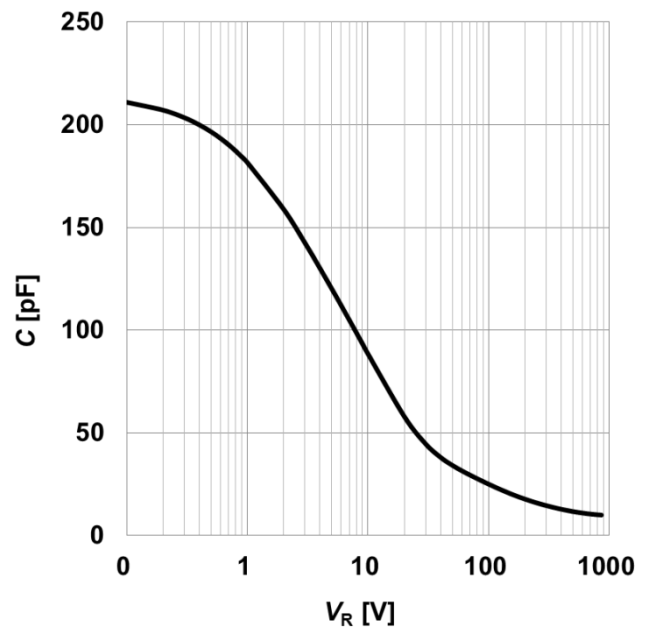


Figure 8. **Typical capacitance as function of reverse voltage**, $C=f(V_R)$; $T_J=25^{\circ}\text{C}$; $f=1\text{ MHz}$

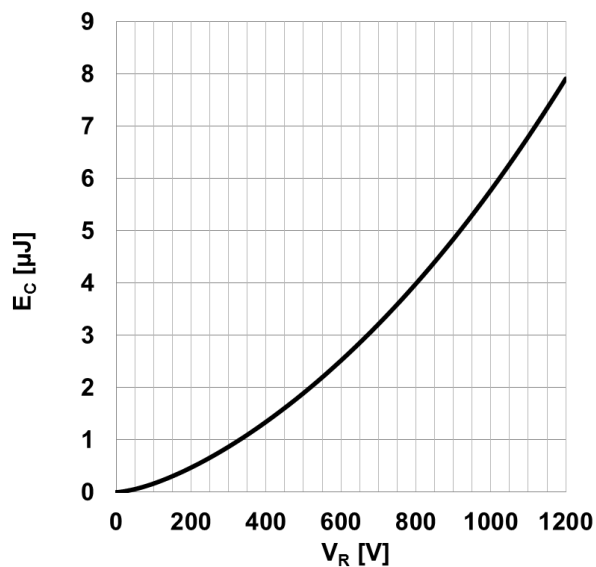
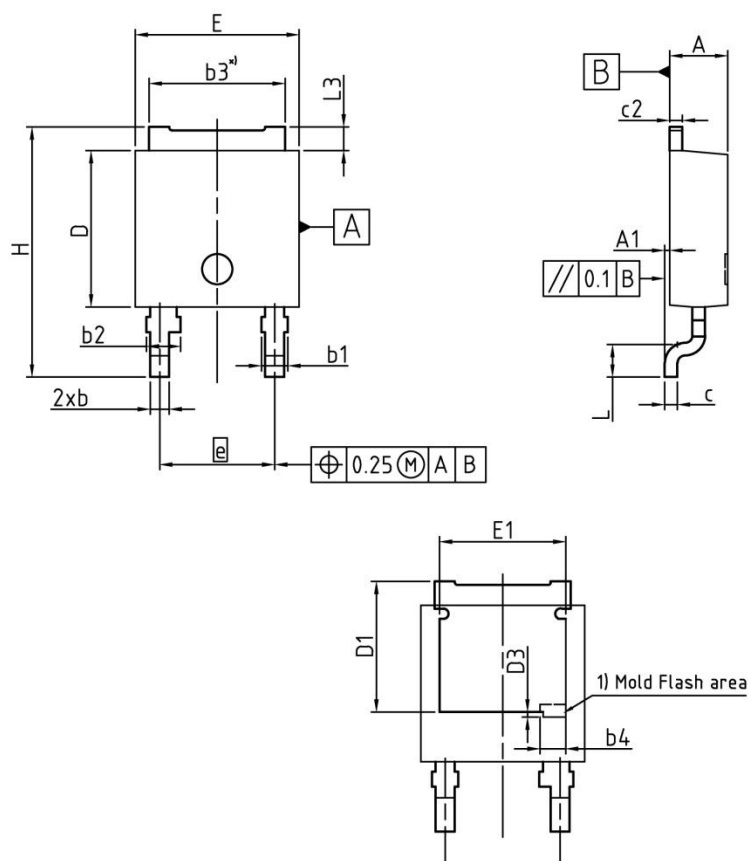


Figure 9. Typical capacitance stored energy as function of reverse voltage,

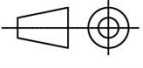
$$E_C = \int_0^{V_R} C(V) V dV$$

PG-TO252-2



*) mold flash not included

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.20	2.35	0.087	0.093
A1	0.00	0.15	0.000	0.006
b	0.65	0.85	0.026	0.033
b1	-	1.15	-	0.045
b2	1.05	1.45	0.041	0.057
b3	5.30	5.50	0.209	0.217
b4	1.02		0.040	
c	0.46	0.58	0.018	0.023
c2	0.46	0.58	0.018	0.023
D	6.02	6.22	0.237	0.245
D1	5.04	5.44	0.198	0.214
E	6.45	6.65	0.254	0.262
E1	5.00		0.197	
e	4.57 (BSC)		0.180 (BSC)	
N	2		2	
H	9.40	10.40	0.370	0.409
L	1.19	1.39	0.047	0.055
D3	0.20		0.008	
L3	0.90	1.10	0.035	0.043

DOCUMENT NO. Z8B00173481
SCALE 0 2.0 4mm
EUROPEAN PROJECTION 
ISSUE DATE 29-05-2014
REVISION 01

Revision History

IDM02G120C5

Revision: 2015-06-22, Rev. 2.0

Previous Revision:

Revision	Date	Subjects (major changes since last version)
2.0	2015-06-22	Final data sheet

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Published by

Infineon Technologies AG

81726 Munich, Germany

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